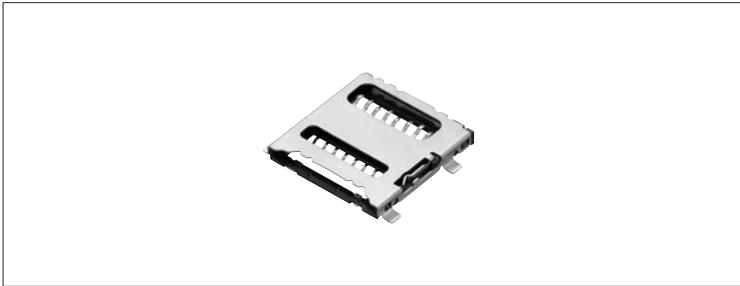


Connector for microSD™ Card (Header Type)

SCHD Series



Low-profile with 1.6mm thickness provides improved flexibility in set design.



For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module

Features

- A comfortable click feel at insertion.
- Card-guide structure for smoother card insertion.

Applications

- For mobile phones and personal digital assistants

Typical Specifications

Items		Specifications
Structure	Applicable media	microSD™ Card
	Mounting type	Surface mounting type
	Mounting style	Standard mount
	Media ejection structure	Manual insertion/removal
Performance	Operating temperature range	-20°C to +70°C
	Voltage proof	500V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	100mΩ max.
	Insertion and removal cycle	10,000cycles

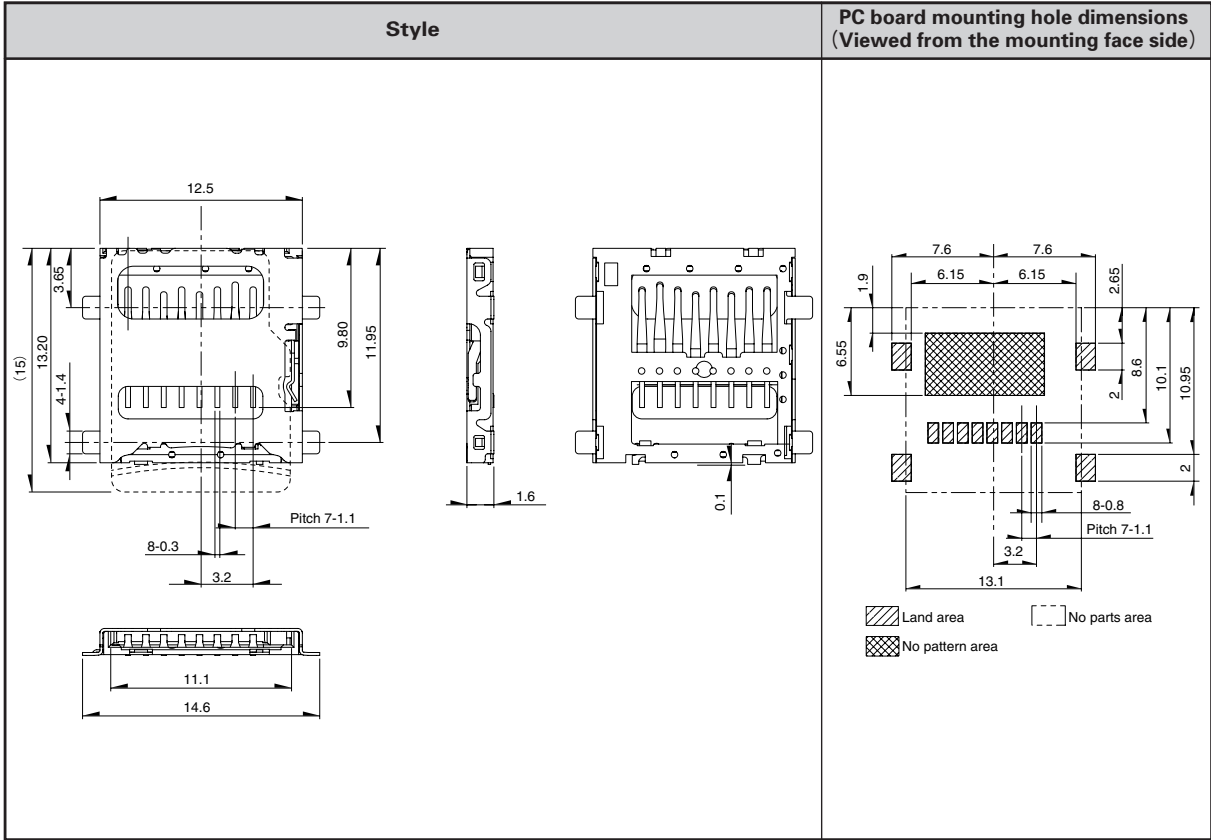
Product Line

Media ejection structure	Mounting system	Stand-off (mm)	Packing system	Product No.
Manual insertion/removal	Standard mount	0	Taping	SCHD1A0101

Dimensions

Unit:mm

- For SD Memory Card
- For microSD™ Card
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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).

For
SD Memory
Card

For
microSD™
Card

For
SIM Card
8pins

For
W-SIM

For
Memory
Stick Micro™

For
Memory
Stick™

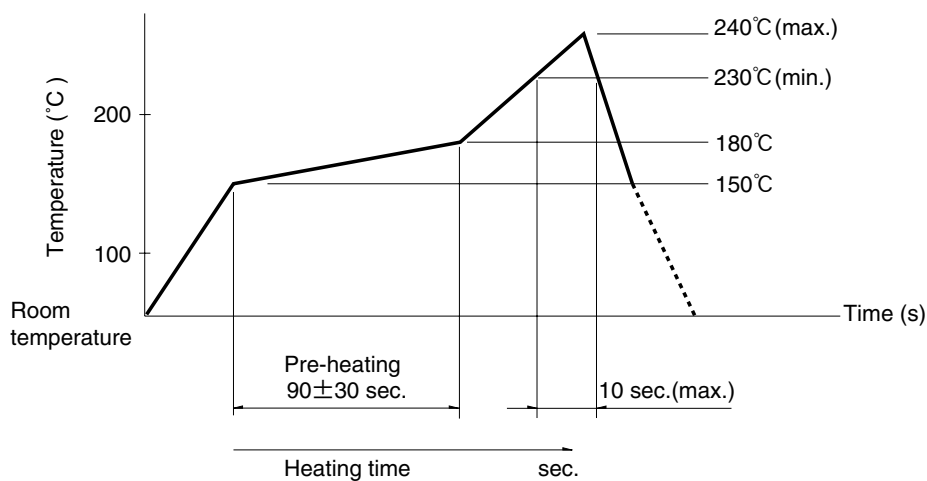
Combine Type

For
Compact
Flash™

For PC cards
supporting
CardBus

For
Express
Card™

For CMOS
Camera Module



Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.